⊠9th "Trento" Workshop on Advanced Silicon Radiation Detectors
 br>(3D and p-type Technologies)

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Book of Abstracts

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Corresponding Author: wermes@uni-bonn.de

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ATLAS Insertable B-Layer (IBL)

Corresponding Author: didier.ferrere@cern.ch

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ALICE Monolithic Pixels

Corresponding Author: petra.riedler@cern.ch

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Performance and upgrade of the LHCb Vertex Detector

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Operational experience and radiation damage at LHC

Corresponding Author: konstantin.toms@cern.ch

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Status overview & Recent Achievements of the ATLAS Upgrade Planar Pixel Sensors R&D Project

Corresponding Author: julia.rieger@cern.ch

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Doping profiles and TCAD simulations of ATLAS planar pixel sensors for IBL upgrade

Corresponding Author: dinu@lal.in2p3.fr

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Future sensor production and sensor-chip packaging technologies at CiS

Corresponding Author: tobias.wittig@cern.ch

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Planar p-type pixel and strip sensors development for HL-LHC in Japan

Corresponding Author: yoshinobu.unno@kek.jp

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Results from beamtests of the new designs of pixel structures

Corresponding Author: daiki.yamaguchi@cern.ch

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Test beam characterization of Ultra-Thin hybrid pixel Timepix assemblies for CLIC Vertex R&D

Corresponding Author: mathieu.benoit@cern.ch

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Corresponding Author: robert.klanner@cern.ch

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Microstrip stacked detectors

Corresponding Author: giulio.pellegrini@cnm.es

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Highlights from IBL 3D Module Production

Corresponding Author: andrea.gaudiello@cern.ch

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Experience with CNM 3D sensors for the ATLAS IBL

Corresponding Author: ivan.lopez.paz@cern.ch

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Discarding low performance 3D sensors before bump bonding

Corresponding Author: sonia.fernandez@cern.ch

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3D silicon pixel detectors for the ATLAS Forward Physics experiment

Corresponding Author: joern.lange@cern.ch

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Characterization of double-sided 3D sensors after proton and neutron irradiation

Corresponding Author: roberto.mendicino@unitn.it

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Characterization and performance of 3D silicon pixel detectors for CMS

Corresponding Author: fabio.ravera@cern.ch

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Characterization of CNM's 3D pixel sensors for the phase-2 upgrade of the CMS vertex detector

Corresponding Author: francisca.javiela.munoz.sanchez@cern.ch

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Test-beam study of the performance of Sintef CMS-2E 3D pixel detectors

Corresponding Author: l.vigani@campus.unimib.it

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Performance Of Thin Edgeless N-on-p Planar Pixel Sensors for ATLAS Upgrades

Corresponding Author: boscardi@fbk.eu

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Development of thin n-in-p pixel modules for the ATLAS upgrade at HL-LHC

Corresponding Author: anna.macchiolo@cern.ch

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Thin Edgeless Pixel Sensors on Epitaxial Wafers After Irradiation

Corresponding Author: ggiacomini@fbk.eu

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Corresponding Author: hartmut@scipp.ucsc.edu

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First measurements of new p-type strip and pad detectors with LGAD in epitaxial wafers

Corresponding Author: marta.baselga@cern.ch

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Simulation of reduced edge planar pixel sensor for the High Luminosity LHC

Corresponding Author: vagelis.gkougkousis@cern.ch

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Corresponding Author: riccardo.mori@cern.ch

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Simulation of Ultra-Fast Silicon Detectors

Corresponding Author: francesca.cenna@cern.ch

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Latest measurements of LGAD diodes fabricated at IMB-CNM

Corresponding Author: virginia.greco@pi.infn.it

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Radiation hardness of Low Gain Amplification Diodes (LGAD)

 $\textbf{Corresponding Author:} \ gregor.kramberger@ijs.si$

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Corresponding Author: cartiglia@to.infn.it

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Compact and Low-Power Time to Digital Converters for High Granularity Silicon Detectors

Corresponding Author: rivetti@to.infn.it

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HV-CMOS Overview

Corresponding Author: ivan.peric@ti.uni-mannheim.de

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Radiation-hard Active Pixel Sensors for HL-LHC Detector Upgrades based on HV-CMOS Technology

Corresponding Author: malte.backhaus@cern.ch

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Particle Tracking with 3D Monolithically Stacked CMOS Active Pixel Sensors

Corresponding Author: daniele.passeri@diei.unipg.it

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Development of thin pixel modules using novel 3D Processing techniques

Corresponding Author: thomas.mcmullen@cern.ch

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Developments of silicon based low temperature detectors (LTD) at Genoa.

Corresponding Author: michele.biasotti@ge.infn.it

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Conclusions and Thanks